

SEMI Standards Staff Report

November 28, 2018 v1.0

SEMI Japan

Contents

- SEMI Global Calendar of Events
- SEMICON Japan 2018
- Global Standards Meeting Schedule
- 2018 Critical Dates for SEMI Standards Ballots
- A&R Ballot Review
- SEMI Standards Publications
- Regulations and Procedure Manual
- JRSC Topics
- SEMI通信 / SEMI Japan e-mail newsletter
- Staff Assignment

SEMI Global 2018 Calendar of Events

Event Name	Event Details
SEMICON[®] WEST	July 10-12 San Francisco, CA
SEMICON[®] TAIWAN	Sept 5-7 Taipei, Taiwan
SEMICON[®] EUROPA	Nov 13-16 Munich, Germany
SEMICON[®] JAPAN	Dec 12-14 Tokyo, Japan

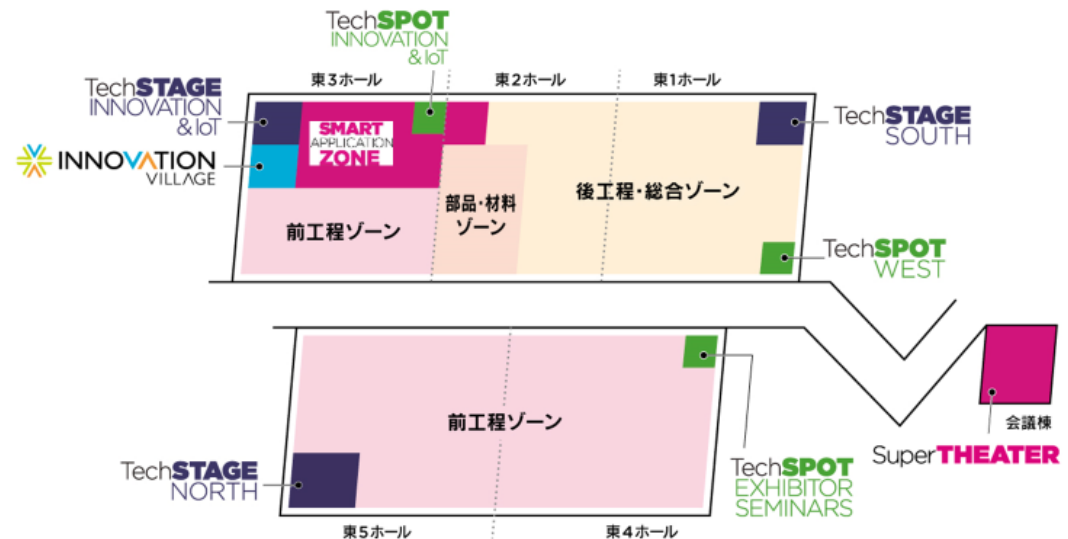
SEMI Global 2019 Calendar of Events

Event Name	Event Details
SEMICON[®] KOREA	Jan. 23 -25, 2019 Seoul. South Korea
SEMICON[®] CHINA	Mar 20-22, 2019 Shanghai, China
SEMICON[®] SOUTHEAST ASIA	May 7-9, 2019 Kuala Lumpur, Malaysia
SEMICON[®] WEST	July 9-11, 2019 San Francisco, California
SEMICON[®] TAIWAN	Sept 18-20, 2019 Taipei, Taiwan
SEMICON[®] EUROPA	Nov XX-XX, 2019 Munich, Germany
SEMICON[®] JAPAN	Dec 11-13, 2019 Tokyo, Japan

SEMICON Japan 2018

- 日時：2018年12月12日（水）～14日（金）
- 会場：東京ビッグサイト
- 規模：780社 1,800小間
- 延べ来場者：70,000名

SEMICON Japan 2018 全体レイアウト



SEMICON Japan Twitter Account

- Please follow us on twitter for SEMICON Japan information.
 - @semicon_jpn



The image shows a screenshot of the SEMICON Japan Twitter account. The header features large Japanese characters 'マシコンが起' and the event dates 'DEC 12-14, 2018 | TOKYO BIG SIGHT |'. Below this is the SEMICON JAPAN mascot, a girl in a pink cap and dress. The profile information includes the name 'SEMICON Japan', handle '@semicon_jpn', and a bio in Japanese. The bio mentions the event is a semiconductor industry showcase. The bio also includes a link to the official Facebook page and the SEMICON Japan website. The tweet section shows a tweet from SEMICON Japan dated November 23rd, asking for the smallest size among three options: (A) CPU processing size, (B) Influenza virus diameter, and (C) Mosquito eye diameter. The tweet includes a photo of a person looking out a window.

マシコンが起
DEC 12-14, 2018 | TOKYO BIG SIGHT |

SEMICON JAPAN

SEMICON Japan
@semicon_jpn

SEMICON Japan マスコットキャラクターのセミコンケイです。セミコン・ジャパンは半導体製造を中心に、エレクトロニクスすべてのサプライチェーンを繋ぐ世界を代表する国際展示会。ここでは半導体産業の動向やイベント最新情報などをお伝えしていきます。公式Facebook: on.fb.me/1a2RbKi

semiconjapan.org

2013年7月に登録

ツイート 1,690 フォロー 341 フォロワー 520 いいね 210 リスト 3

ツイート ツイートと返信 メディア

SEMICON Japan @semicon_jpn · 11月23日
【金曜日はクイズの日】
以下の中で一番サイズが小さいのはどれ？
(A) 最先端スマホのCPUの加工寸法
(B) インフルエンザウイルスの直径
(C) 蚊の単眼の直径



スタンダード会議（技術委員会 & JRSC）

- JRSC (Invitation Only)
 - Tuesday, December 11 SEMI (Japan office)
- Liquid Chemicals
 - Wednesday, December 12, 13:00-15:00
- Traceability
 - Wednesday, December 12, 10:00-12:00
- Physical Interfaces & Carriers
 - Wednesday, December 12, 14:00-17:00
- Metrics
 - Thursday, December 13, 13:00-17:00
- Silicon Wafers
 - Thursday, December 13, 14:00-17:00
- Information & Control
 - Friday, December 14, 13:00-17:00
- Environmental, Health & Safety
 - Friday, December 14, 13:00-16:00

SEMIスタンダード授賞式 フレンドシップパーティ

12月13日(木) 17:30-19:00

会議棟 6F 608 会議室

本年度受賞者

功労賞

榎並弘充氏（日立ハイテクノロジーズ）

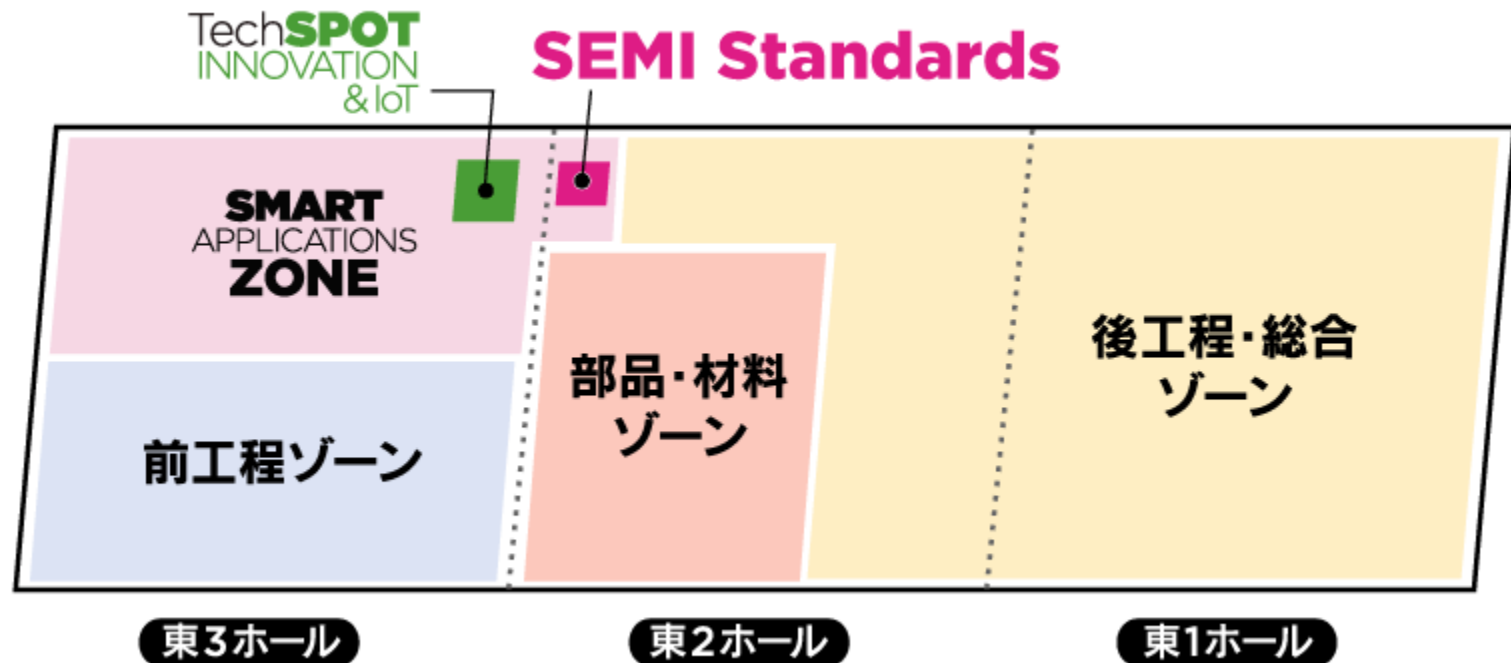
鈴木勲氏（日本エム・ケー・エス）

スタンダード関連セミナー

- IoTとサプライチェーンのトレサビリティ
 - 12月12日（水） 11:00-12:40
 - 会議棟6階 607
- EDA Workshop
 - 12月12日（水） 14:00-17:00
 - 会議棟6階 607
- 半導体工場運用のスマート化を向上させるSEMIのファクトリー・オートメーション・スタンダード
 - 12月12日（水） 11:20-12:10
 - 東3ホールTechSPOT/INNOVATION&IOT
- PLPの展開を加速するための課題 ー何を規格化すべきか？ー
 - 12月13日（木） 10:20-11:10
 - 東3ホールTechSPOT/INNOVATION&IOT
- コネクティッド・ファクトリーを実現するスマートM2MインターフェイスSEMI A1
 - 12月13日（木） 11:20-12:10
 - 東3ホールTechSPOT/INNOVATION&IOT

スタンダード・ブース SEMI Standards

3D パッケージングに関する情報や半導体製造、SMTなどの製造ラインをスマート化するSEMIのスタンダード群の紹介



Global Standards Meeting Schedule

<http://www.semi.org/en/standards-events>

- November 30, 2018
Gases Japan TC Chapter and Facilities Japan TC Chapter Joint Meeting
SEMI Japan Office
- November 5-8, 2018
NA Standards Fall 2018 Meetings
SEMI HQ in Milpitas, California, USA
- November 13-14, 2018
Europe Standards Meetings
ICM, Munich, Germany
- December 11-14, 2018
SEMICON Japan 2018 Standards Meetings
SEMI Japan Office(December 11)
Tokyo Big Sight, Tokyo, Japan (December 12-14)
- December 18, 2018
3D Packaging and Integration Taiwan TC Chapter
SEMI Taiwan Office
- December 19, 2018
Photovoltaic Taiwan TC Chapter
ITRI Office
- December 19, 2018
Automation Technology Japan TC Chapter
SEMI Japan Office
- December 21, 2018
FPD Metrology Taiwan TC Chapter
ITRI Office
- January 24, 2019
Information & Control Korea TC Chapter
COEX, in conjunction with SEMICON Korea 2019
- February 8, 2019
FPD Materials & Components Japan TC chapter
SEMI Japan Office
- February 20, 2019
Automation Technology Taiwan TC Chapter
SEMI Taiwan Office
- February 22, 2019
3D Packaging and Integration Japan TC Chapter
SEMI Japan Office
- March, 2018 (Tentitive)
Information & Control Taiwan TC Chapter
SEMI Taiwan Office
- March 20, 2019
EHS Taiwan TC Chapter
SEMI Taiwan Office
- March 29, 2019
HB-LED China TC Chapter
SEMI China Office
- April, 2019 (Tentitive)
NA Standards Spring 2019 Meetings
SEMI HQ in Milpitas, California, USA
- April 26, 2019
PV & PV Materials China TC Chapter
SEMI China Office

2018 Critical Dates for SEMI Standards Ballots







2018	Ballot Submission Deadline	Voting Opens	Voting Closes
Cycle 8	Oct 12	Oct 26	Nov 26
Cycle 9	Nov 14	Nov 28	Dec 28

<http://www.semi.org/en/Standards/Ballots>

2019 Critical Dates for SEMI Standards Ballots

2018	Ballot Submission Deadline	Voting Opens	Voting Closes
Cycle 1	Jan 3	Jan 16	Feb 15
Cycle 2	Feb 1	Feb 15	Mar 18
Cycle 3	Mar 12	Mar 26	Apr 25
Cycle 4	Apr 16	Apr 30	May 30
Cycle 5	May 10	May 24	Jun 24
Cycle 6	July 19	July 31	Aug 30
Cycle 7	Aug 22	Sept 4	Oct 4
Cycle 8	Oct 11	Oct 25	Nov 25
Cycle 9	Nov 14	Nov 26	Dec 26

A&R Ballot Review (2018)

A&R Cycle	Result	Notes
January 2018	 ISCA&RSCJan2018WebVotingSummaryv	5880: failed. Reason: The TC Chapter review of the Letter Ballot took place and completed on a date other than the date described in the Background Statement of the Letter Ballot, which is violation of ¶ 9.5 of the Regulations.
March 2018	 ISCA&RSCMarch2018WebVotingSummary	All passed.
May 2018	 ISCA&RSCMay2018WebVotingSummary	All passed
July 2018	 ISCA&RSCJuly2018WebVotingSummary	6302A-LI1, 6304A, 6305A-LI1, 6306A-LI1, 6307A-LI1 and 6308A-LI1 failed. Reasons: -Identical situation for all six documents -A number of procedural requirements were not followed in the re-balloting of these documents -Regarding a Negative that pointed out legitimate procedural issues as “Not Related” is procedurally wrong
Aug. 2018	 ISCA&RSCAugust2018WebVotingSummary	6333-LI1, -LI2, LI3 failed. 6374 and 6376 should be on hold until an editorial change to include a footnote references the organization that has ownership of the trademark is implemented.
Oct. 2018	 ISCA&RSCOct2018WebVotingSummary	All passed

SEMI Standards Publications

Cycle	New	Revised	Reapproved	Withdrawn
April 2018	0	9	2	0
May 2018	0	3	5	0
June 2018	2	14	11	0
July 2018	0	3	21	0
August 2018	2	11	4	0
September 2018	0	8	1	0
October 2018	7	8	12	0

- Total SEMI Standards in portfolio: 996
 - Includes 252 Inactive Standards

SEMI Standards Publications

New Standards

Cycle	Designation	Title	Committee	Region
June 2018	SEMI C96	Test Method for Determining Density of Chemical Mechanical Polish (CMP) Slurries	Liquid Chemicals	NA
June 2018	SEMI D77	Test Method for Measurements of Dimension of Films for FPD – Contour Matching Method	FPD Materials & Components	JA
August 2018	SEMI PV84	Test Method for Polymer Foil Dependent Discoloration of Silver Fingers on Photovoltaic Modules	Photovoltaic	China
August 2018	SEMI HB09	Test Method and Acceptance Criteria for Visual Inspection of Surface Defects of GaN Epitaxial Wafers Used for Manufacturing HB-LED	HB-LED	China

SEMI Standards Publications

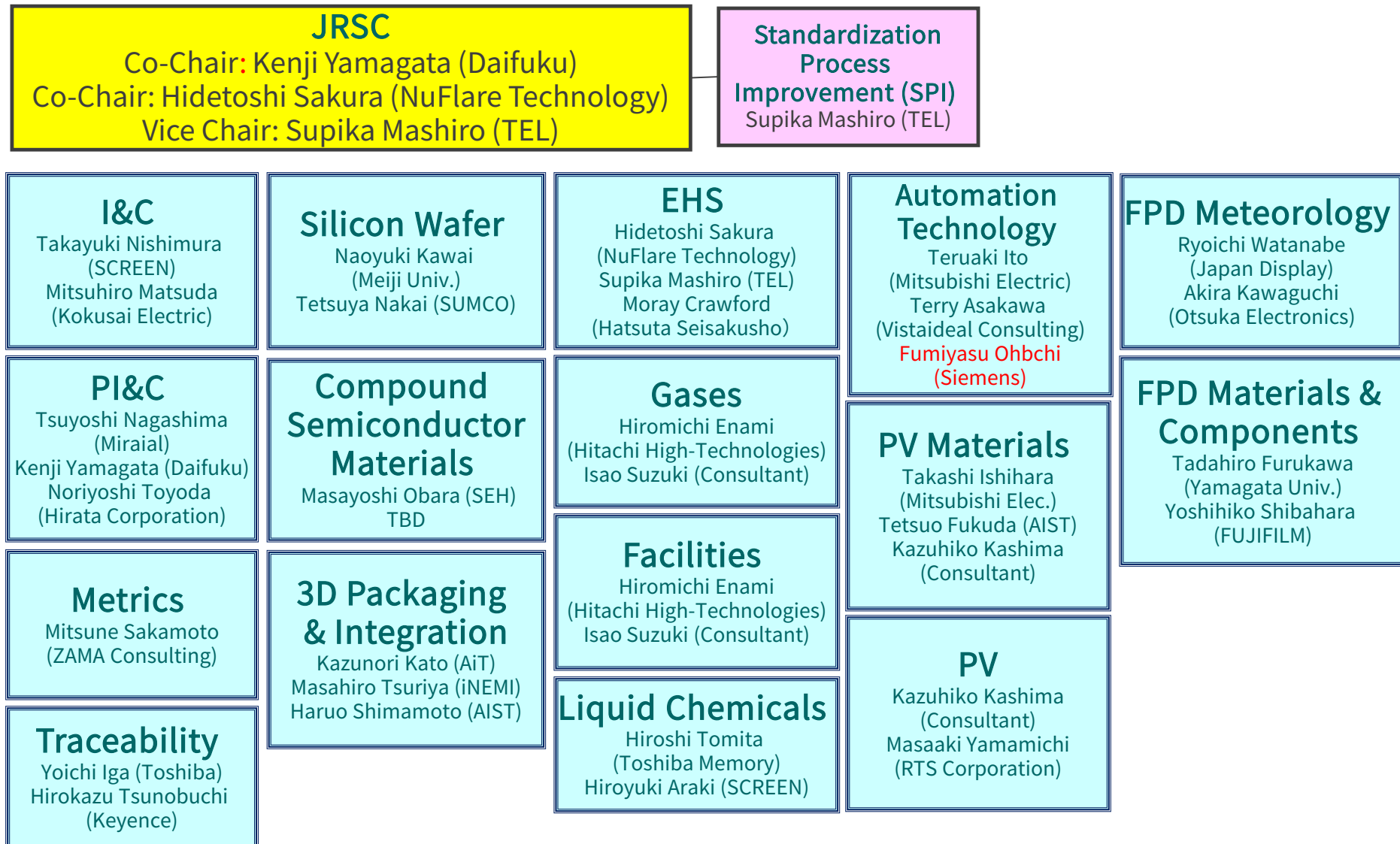
New Standards

Cycle	Designation	Title	Committee	Region
October 2018	SEMI 3D18	Guide for Wafer Edge Trimming for 3DS-IC Process	3D Packaging & Integration	Taiwan
October 2018	SEMI D78	Test Method of Water Vapor Barrier Property for Plastic Films with High Barrier for Electronic Devices	FPD - Materials & Components	Japan
October 2018	SEMI HB10	Specification for Single Crystal Sapphire Intended for Use for Manufacturing HB-LED Wafers	HB-LED	China
October 2018	SEMI PV85	Practice for Metal Wrap Through (MWT) Back Contact Photovoltaic (PV) Module Assembly	Photovoltaic	China
October 2018	SEMI PV86	Specification for Crystalline Silicon Photovoltaic Module Dimensions	Photovoltaic	China
October 2018	SEMI PV87	Test Method for Peeling Force Between Electrode and Ribbon/Back Sheet	Photovoltaic	China
October 2018	SEMI PV88	Test Method for Determination of Hydrogen in Photovoltaic (PV) Polysilicon by Inert Gas Fusion Infrared Absorption Method	Photovoltaic	China

JRSC Topics

- Membership
 - New AT Japan TC Chapter Co-chair
 - シーメンス（株）大渕文晴氏
- 2018年度プランニング会議
 - 開催日時：2018年8月24日（金）13:30-17:30
 - 場所：SEMIジャパン会議室
 - 参加者 :19名
 - 委員長、タスクフォースリーダー、スタッフ、その他興味のあるメンバー
 - トピックス：
 - 規約改訂内容解説
 - Virtual Meeting模擬会議実施
 - Fire Appにおける参加者認証、投票および投票集計機能は評価できるが、会議運営上必要な機能およびその表示の仕方については課題がまだ沢山ある。
 - Fire Appの階層化なども含め今回の出された課題をフィードバックする。
 - 会議後懇親会

JRSC Organization Chart



SEMI通信 (2018年)

テーマ募集中!!

- 2018_01_2017年度SEMIジャパン・スタンダード賞はSCREENセミコンダクターソリューションズの西村剛幸氏が受賞
- 2018_02_3D Packaging & Integrationグローバル技術委員会の始動とPLPパネルサイズ規格化の取り組み状況
- 2018_03_レガシーなパッケージ技術から三次元チップ実装技術、さらにFan-out Wafer LevelやPLP技術への標準化活動の遍歴について
- 2018_04_Fan-Out Wafer LevelやPLP技術への標準化活動の具体的な取り組み状況
- 2018_05_次世代SEMI Equipment Data Acquisition (EDA) スタンダードより良く、より効率的なデータ転送のためのHTTP/2技術の適用
- 2018_06_スマートファクトリーのための業界コラボレーション - SMT-PCBパネルとその関連情報とを転送するマシンツーマシン (M2M) 通信インターフェース標準の開発に関するJARAとSEMIのコラボレーション
- 2018_07_FO-PLP製造工程及び主な技術課題についての紹介
- 2018_08_FO-WLP/PLPに使われるキャリア材及び基板材料の技術紹介と課題について
- 2018_09_SEMI D77-0618: 輪郭照合法を用いた、異型偏光板の形状測定方法の標準化について
- 2018_10_半導体工場のスマート・マニュファクチャリング実現にむけた次世代のレシピ・セキュリティ
- 2018_11_FO-PLP Panel Level Packageの標準化活動/材料紹介

Global Staff Assignment - Japan

- Mizue Iwamura
 - Automation Technology
 - Information & Control
 - Facilities
 - Gases
 - Liquid Chemicals
 - Photovoltaic
 - Photovoltaic Materials
- Junko Collins
 - Compound Semiconductor Materials
 - Silicon Wafer
 - (JRSC)
- Chie Yanagisawa
 - 3D Packaging & Integration
 - EHS
 - FPD M&C
 - FPD Meteorology
 - Metrics
 - Physical Interfaces & Carriers
 - Traceability

Global Staff Assignment - North America

- Kevin Nguyen
 - Compound Semiconductor Materials
 - EHS
 - Microlithography
 - Photovoltaic
 - Photovoltaic Materials
 - Silicon Wafer
- Inna Skvortsova
 - Automated Test Equipment
 - HB-LED
 - Information & Control
 - Liquid Chemicals
 - Metrics
 - Traceability
- Laura Nguyen
 - 3D Packaging & Integration
 - Facilities
 - Gases
 - MEMS / NEMS
 - Physical Interfaces & Carriers

Global Staff Assignment – Other regions

- China
 - Isadra Jin
 - HB-LED
 - PV
 - PV Materials
- EU
 - James Amano and Kevin Nguyen
 - Automation Technology
 - Compound Semiconductor Materials
 - Gases
 - Information & Control
 - Liquid Chemicals
 - Metrics
 - Physical Interfaces & Carriers
 - PV Materials
 - Silicon Wafer
- Korea
 - Natalie Shim
 - Facilities
 - FPD Metrology
 - FPD Materials & Components
 - Information & Control
- Taiwan
 - Dean Chang, Tiffany Huang
 - 3D Packaging & Integration
 - Automation Technology
 - EHS
 - FPD Metrology
 - Information & Control
 - PV

Global Staff Assignment - International

- James Amamo
 - ISC
- Kevin Nguyen
 - Regulation
 - Audit & Review

The background of the slide is a solid red color. It features several white hexagonal shapes of varying sizes and opacities scattered across it. Some hexagons are solid white, while others are semi-transparent, creating a layered effect. The hexagons are positioned in the upper and middle sections of the slide, with some appearing near the top edge and others further down.

Thank you